Materials Declaration

Package	MQFP
Body Size	32 X 32 X 3.5 (+2.6)
LeadCount	240
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica fused	81.00	4.93 E+00	668918
Epoxy Cresol Novolac	9.50	5.79 E-01	78453
Phenol Novolac	6.00	3.65 E-01	49550
Brominated Epoxy resin	1.60	9.74 E-02	13213
Antimony trioxide	1.50	9.13 E-02	12387
Carbon black	0.40	2.44 E-02	3303

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	95.90	1.00 E+00	136097
Ni	3.20	3.35 E-02	4541
Si	0.73	7.59 E-03	1029
Mg	0.18	1.83 E-03	248

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	9.60 E-03	1302

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	4.05 E-02	5493

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.73 E-02	10485

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.94 E-02	13481

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Silver filler	75.50	8.34 E-03	1131
Diglycidylether bisphenol-F	10.50	1.16 E-03	157
Epoxy resin	6.00	6.63 E-04	90
Gamma Butyrolactone	5.00	5.52 E-04	75
Mixed aryl allyl glycidyl compounds	3.00	3.31 E-04	45

Package Totals

Weight (g)	PPM
7.37 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP-OES
Cd	None Detected	US EPA 3052. ICP-OES
Hg	None Detected	US EPA 3052. ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3	US EPA 3052. ICP-OES
Cd	None Detected	US EPA 3052. ICP-OES
Hg	None Detected	US EPA 3052. ICP-OES
Cr+6	None Detected	US EPA 3060A & 7196A. UV-VIS
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Materials Declaration

Package	MQFP
Body Size	32 X 32 X 3.5 (+2.6)
LeadCount	240
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica fused	75.0	4.57 E+00	636181
Epoxy Cresol Novolac	10.0	6.09 E-01	84824
Phenol Novolac	6.5	3.96 E-01	55136
Antimony trioxide	3.0	1.83 E-01	25447
Brominated Epoxy Resin	2.0	1.22 E-01	16965
Carbon Black	0.3	1.83 E-02	2545

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.28	1.04 E+00	144718
Cr	0.22	2.30 E-03	321
Sn	0.25	2.62 E-03	364
Zn	0.25	2.62 E-03	364

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	9.60 E-03	1338

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	3.44 E-02	4796
Pb	15.0	6.08 E-03	846

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.73 E-02	10770

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.94 E-02	13847

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75.0	8.29 E-03	1154
Resin	20.0	2.21 E-03	308
Curing agent & hardener	5.0	5.52 E-04	77

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3050B. ICP-AES
Cd	None Detected	BS EN1122:2001 Method B. ICP-AES
Hg	None Detected	US EPA 3052. ICP-AES
Cr+6	None Detected	US EPA 3060A & 7196A
PBB	None Detected	Analysis was performed by GC/ECDMS or HPLC/DAD/MS
PBDE	None Detected	Analysis was performed by GC/ECDMS or HPLC/DAD/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3050B, ICP-AES
Cd	None Detected	US EPA 3050B, ICP-AES
Hg	None Detected	US EPA 3052, ICP-AES
Cr+6	None Detected	EPA 3060A, UV-VIS
PBB	None Detected	USEPA 3450C. Analysis performed by GC/MS
PBDE	None Detected	USEPA 3450C. Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
7.18 E+00	1000000

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